

# YourPCB PCB Manufacturing Capability

Corrected engineering capability overview for PCB manufacturing, DFM review and international RFQ evaluation.

Capability Item	Standard Capability	Advanced Capability	Premium / Engineering Capability
Materials	FR-4, High-Tg FR-4, Polyimide, Low Dk, BT-Resin	FR-4, High-Tg FR-4, Polyimide, Low Dk, BT-Resin, PTFE	FR-4, High-Tg FR-4, Polyimide, Low Dk, BT-Resin, PTFE
Impedance control tolerance	+/-10%	+/-8%	+/-5%
Inner layer line width	0.003" / 0.075mm	0.0024" / 0.06mm	0.0016" / 0.04mm
Outer layer line width	0.0036" / 0.09mm	0.0028" / 0.07mm	0.0024" / 0.06mm
BGA pitch support	0.016" / 0.4mm	0.012" / 0.3mm	0.008" / 0.2mm
ENIG thickness	1.2u" / 0.03um	8u" / 0.2um	10u" / 0.25um
Electrolytic gold plating	20u" / 0.5um	50u" / 1.27um	60u" / 1.5um
Layer count	Up to 30 layers	Up to 50 layers	Up to 60 layers
Minimum mechanical drill	0.006" / 0.15mm	0.005" / 0.125mm	0.003" / 0.075mm
Maximum panel size	24.0" x 26.0" / 610 x 660mm	24.4" x 28.3" / 620 x 720mm	24.4" x 28.3" / 620 x 720mm
Maximum board thickness	0.189" / 4.8mm	0.236" / 6mm	0.275"+ / 7mm+
High aspect ratio support	Up to 24:1	Up to 30:1	Up to 35:1
Registration capability	0.003" / 0.075mm	0.0016"-0.002" / 0.04-0.05mm	0.0012"-0.0016" / 0.03-0.04mm
Special processes	Plugging, Back Drill, Laser Drill, 1+N+1 HDI	Plugging, Back Drill, Laser Drill, 2+N+2 HDI	Plugging, Back Drill, Laser Drill, 4+N+4 HDI